

WHAT IS CLAIMED IS:

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1. An electronic surface mount package comprising:
a one piece construction package having an open bottom,
a plurality of toroid transformers carried within said
package, said toroid transformers each having wires wound
thereon,
a plurality of terminal pins molded within said
package, each of said pins having a notched post upon which
said wires from said transformers are wrapped and soldered
thereon, respectively, and
at least one reinforcement beam located laterally along
the bottom of said package to provide improved mechanical
strength of said package.
2. An electronic surface mount package comprising:
A construction package having an open bottom,
a plurality of toroid transformers carried within said
package, said toroid transformers each having wires wrapped
thereon,
a plurality of terminal pins molded within said
package, each of said pins having a notched post upon which
said wires from said transformers are wrapped and soldered
thereon, respectively, and
at least one reinforcement beam located laterally along
the bottom of said package to provide improved mechanical

strength of said package.

3. A package as in Claim 2 wherein said construction package is one piece.

4. The package of Claim 3 wherein said construction package has an open bottom.

5. The package of Claim 4 wherein said posts are separated from one another so as to avoid arcing.

6. An electronic surface mount package for mounting on a printed circuit board in an electronic device, said electronic surface mount package comprising:

a one piece construction package,

a plurality of toroid transformers carried within said package, said toroid transformers each having wires wound thereon,

a plurality of terminal pins molded within said package, each of said pins having a notched post upon which said wires from some transformers are wrapped and soldered thereon, respectively, and

at least one reinforcement beam located laterally along the bottom of said package to provide improved mechanical strength of said package.

7. The package as in Claim 6 further including a standoff for maintaining a distance between said terminal pins and said printed circuit board.

8. An electronic surface mount package for mounting on a printed circuit board in an electronic device, said package comprising:

a one piece open construction package,
a plurality of toroid transformers carried within said package, said toroid transformers each having wires wound thereon,
a plurality of terminal pins molded within said package, each of said pins having a hour-glass shaped notched post upon which said wires from said transformers are wrapped thereon, respectively.

9. An electronic surface mount package comprising:

a one piece open construction package,

a plurality of toroid transformers carried within said package by a soft silicon type material, said toroid transformers each having wires wound thereon,

a plurality of terminal pins molded within and extending from the bottom of said package, each of said pins having a notched post upon which said wires from said transformers are wrapped and soldered thereon, respectively.

10. An electronic surface mount package comprising:

a construction package having an open bottom,

a plurality of toroid transformers carried within said package by a soft silicon type material, said toroid transformers each having wires wound thereon,

a plurality of terminal pins molded within said package, each of said pins having a notched post upon which said wires from said transformers are wrapped and soldered thereon, respectively.

11. An electronic surface mount package for mounting on a printed circuit board in an electronic device, said electronic surface mount package comprising:

a one piece open construction package,

a plurality of toroid transformers carried within said package by a soft silicon type material, said toroid transformers each having wires wound thereon,

a plurality of terminal pins molded within said package, each of said pins having a notched post upon which said wires from said transformers are wrapped and soldered thereon, respectively.

12. The package as in Claim 11 further including a standoff for maintaining a distance between the bottom of said pins and said printed circuit board.

13. An electronic surface mount package comprising:

an open construction package,

at least one toroid transformer carried within said package by a soft silicon type material, said toroid transformer having a wire wound thereon,

at least one terminal pin molded within said package, said pin having a notched post upon which said wire from said transformer is wrapped and soldered thereon.